


NUMBER <b>GS-12-645</b>	TYPE <b>PRODUCT SPECIFICATION</b>		
TITLE <b>0.5mm Pitch FPC/FFC Connector SFV__R-1/2STE_HLF</b>		PAGE <b>1 of 10</b>	REVISION <b>B</b>
		AUTHORIZED BY <b>Sei Watanabe</b>	DATE <b>2010-2-19</b>
		CLASSIFICATION <b>UNRESTRICTED</b>	

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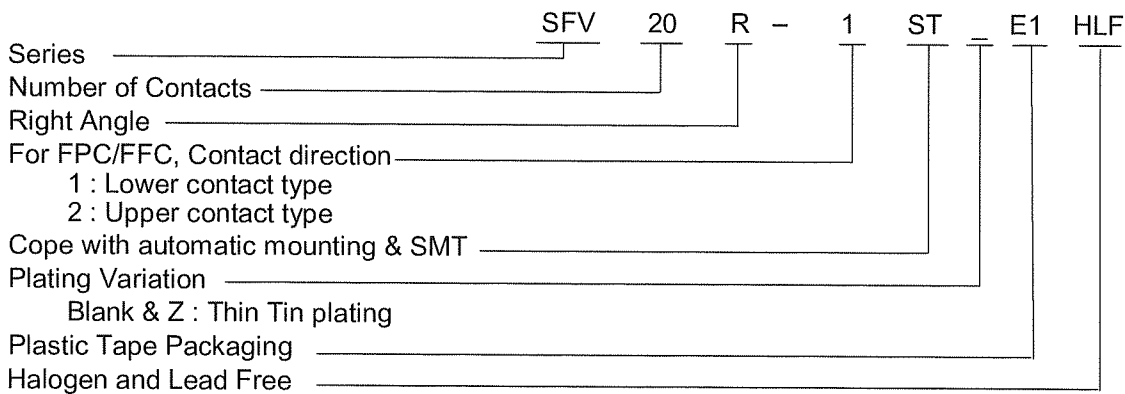
1. SCOPE

This specification covers the requirements for the connector (SFV\_\_R-1/2ST\_E\_HLF ) with 0.5mm spacing to which the edge of FPC(Flexible Printed Circuit) and FFC(Flexible Flat Cable) can be connected by Zero-Insertion-Force method and which copes with automatic mounting and SMT.

2. APPLICABLE STANDARDS

- JIS C 5402 Method for Test of Connectors for Electronic Equipment
- JIS C 0806 Packing of Electronic Components on Continuous Tapes (Surface Mount Components)
- UL - 94 TESTS FOR FLAMMABILITY OF PLASTIC MATERIALS FOR PARTS IN DEVICES AND APPLIANCES.

3. CATALOG No. STRUCTURE



4. CONNECTOR SHAPE, DIMENSIONS AND MATERIALS

See attached drawings.

5. ACCOMMODATED CONDUCTORS (FPC/FFC)

See attached drawings.

6. PACKAGING CONDITION

See attached drawings.

7. RECOMMENDED MOUNTING PATTERN DIMENSIONS

See attached drawings.

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## 8. RATING

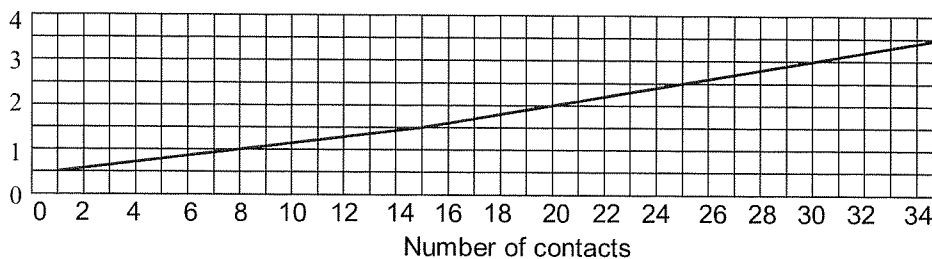
8-1. Voltage : A.C.50V D.C.50V

8-2. Current : A.C.0.5A D.C.0.5A (Refer to the following note.)

8-3. Operating Temperature : -55°C ~ +105°C (Including terminal temperature rises)

### NOTE


Allowable maximum current for one contact is 0.5A. Total allowable current for a whole connector is the value which is shown in the following figure.



## 9. PERFORMANCE CHARACTERISTICS

### 9-1. Electrical Performance


No.	Test Item	Test Method	Requirements
9-1-1	Contact resistance	<p>1) Measure contact resistance between <math>V_1</math>-<math>V_2</math> by voltage drop method by the following circuit by mating accommodated conductor specified in clause 5 after reflow soldering the connector on the P.C.B.</p> <p>2) Open circuit voltage : Less than A.C.20mV 3) Test current : Less than A.C.20mA</p>	<p>1) Initial value : Less than 30mΩ 2) Contact resistance after the test is in accordance with the value specified in each test item.</p>

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9-1-2	Insulation resistance	1) Measure insulation resistance between adjacent contacts in a connector individual. 2) Test voltage : D.C.500V 3) Read value one minute after applying test voltage.	1) More than 100M $\Omega$
9-1-3	Dielectric withstanding voltage	1) For one minute, apply A.C.200V between adjacent contacts in a connector individual. 2) Set current : A.C.1mA	1) Free from any short circuit and insulation breakdown.

9-2. Mechanical Performance

No.	Test Item	Test Method	Requirements
9-2-1	Durability (Slider operation)	1) Measure contact resistance before and after the test by the method in clause 9-1-1 by mating the accommodated conductor specified in clause 5. 2) Number of slider open and close : 20 times (Insert and extract the conductor for each opening of the slider.)	1) Initial contact resistance : Less than 30m $\Omega$ 2) Contact resistance after the test : Less than 50m $\Omega$ 3) Free from any defect such as break etc. on the connector and conductor.
9-2-2	Vibration (Sinusoidal)	JIS C 60068-2-6 (IEC60068-2-6) 1)Frequency range : 10 ~ 500Hz 2)Amplitude : 0.75mm or Acceleration : 100m/s <sup>2</sup> 3)Sweep rate : 1 octave/minute 4)Kind of test : Sweep endurance test 5)Test time : 10 cycles	1) During the test, no circuit opening for more than 1 $\mu$ s. 2) Free from any defect such as break, deformation, loosening and falling off etc. on each portion of the connector.

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9-3. Environmental Performance


No.	Test Item	Test Method	Requirements
9-3-1	Damp heat (Steady state)	JIS C 60068-2-78 (IEC60068-2-78) 1) Measure contact resistance before and after the test by the method in clause 9-1-1 by using the accommodated conductor specified in clause 5. 2) Measure insulation resistance after the test by the method in clause 9-1-2. 3) Bath temperature : 40°C 4) Bath humidity : 90 ~ 95%(relative humidity) 5) Period of exposure : 48 hours 6) Expose conductor and connector in mated condition and leave them under normal temperature.(Without insertion and separation)	1) Initial contact resistance : Less than 30mΩ 2) Contact resistance after the test : Less than 50mΩ 3) Insulation resistance after the test : More than 100MΩ
9-3-2	Salt spray	JIS C 60068-2-11 (IEC60068-2-11) 1) Measure contact resistance before and after the test according to the method in clause 9-1-1 by using accommodated conductor specified in clause 5. 2) Salt solution concentration : 5% 3) Period of exposure : 48 hours 4) Expose conductor and connector in mated condition and leave them under normal temperature after posttreatment. (24 hours)	1) Initial contact resistance : Less than 30mΩ 2) Contact resistance after the test : Less than 50mΩ

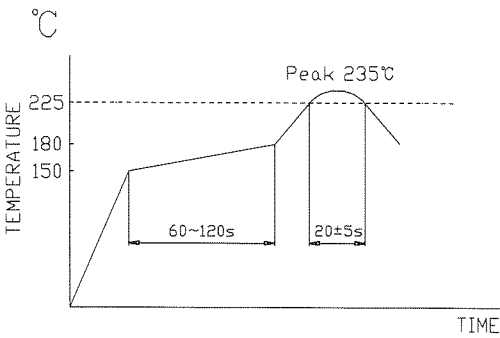
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9-3-3	Change of temperature	<p>JIS C 0025 (IEC60068-2-14)</p> <p>1) Measure contact resistance before and after the test according to the method in clause 9-1-1 by using accommodated conductor specified in clause 5.</p> <p>2) One cycle of temperature is as follow and test 5 cycles.</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Step</th> <th>Temp.(°C)</th> <th>Time(min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-55±3</td> <td>30</td> </tr> <tr> <td>2</td> <td>25±2</td> <td>2 ~ 3</td> </tr> <tr> <td>3</td> <td>85±2</td> <td>30</td> </tr> <tr> <td>4</td> <td>25±2</td> <td>2 ~ 3</td> </tr> </tbody> </table> <p>3) Expose conductor and connector in mated condition and leave them under normal temperature.</p>	Step	Temp.(°C)	Time(min.)	1	-55±3	30	2	25±2	2 ~ 3	3	85±2	30	4	25±2	2 ~ 3	<p>1) Initial contact resistance : Less than 30mΩ</p> <p>2) Contact resistance after the test : Less than 50mΩ</p> <p>3) Free from any defect such as crack, warping and deformation etc. on each portion the connector.</p>
Step	Temp.(°C)	Time(min.)																
1	-55±3	30																
2	25±2	2 ~ 3																
3	85±2	30																
4	25±2	2 ~ 3																

9-4. Other performance

No.	Test Item	Test Method	Requirements
9-4-1	Soldering (Resistance to reflow soldering)	<p>JIS C 60068-2-58 (IEC60068-2-58)</p> <p>1) Solder by setting reflow bath on the following condition.</p> <p>2) Preheating: 150~180°C, 120±5 s</p> <p>3) Soldering : 220°C min. 60s max.</p> <p>4) Peak : 245°C min. 20s max. (Peak 255°C max.)</p> <p>NOTE: Temperature must be measured at contact terminal portion and peak temperature on the upper surface of P.C.B must be less than 260°C.</p> <p>5) Solder paste to be used is JIS Z 3282 Sn96.5Ag3.0Cu0.5</p>	<p>1) Contact resistance after the test : Less than 50mΩ</p> <p>2) Insulation resistance after the test : More than 100MΩ</p> <p>3) No short circuit and insulation breakdown for dielectric withstanding voltage test after this test.</p> <p>4) Free from any damage on performance and contact performance after soldering.</p>
		<p><u>Diagram A</u></p> <p style="text-align: center;">Resistance to reflow soldering profile</p>	

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9-4-2	Soldering (Solderability) (Reflow)	<p>JIS C 60068-2-58 (IEC60068-2-58)</p> <p>1) Solder by setting reflow bath on the following condition.</p> <p>2) Preheating: 150~180°C, 60~120s</p> <p>3) Soldering : 225°C min., 20±5s (Peak 235°C max.)</p> <p>NOTE : Temperature must be measured at contact terminal portion and peak temperature on the upper surface of P.C.B must be less than 260°C.</p> <p>4) Solder paste to be used is JIS Z 3282 Sn96.5Ag3.0Cu0.5</p>	1) Actual soldered area must be more than 90% of the dipped area intended to be soldered.
		<p><u>Diagram B</u></p>  <p style="text-align: center;">Solderability profile</p>	
9-4-3	Conductor retention force (Reference)	<p>1) Measure initial retention force after inserted and locked by using accommodated conductor specified in clause 5.</p> <p>*FCI Test FPC : t=0.33mm Tin plating</p>	<p>1) More than 0.59N/contact for FPC (More than 60gf/contact for FPC)</p> <p>2) More than 0.39N/contact for FFC (More than 40gf/contact for FFC)</p>



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## 10. INDICATION AND PACKAGING

### 10-1. Indication

- 1) Catalog number and lot number are not be indicated on the connector.
- 2) Catalog number and quantity shall be indicated on the surface of the package box.

### 10-2. Packaging

- 1) The connector individuals are packed by tapes with specified quantity in accordance with [JIS C 0806 "Packaging of Electronic Components on Continuous Tapes (Surface Mount components)" ] and put into package box in accordance with FCI JAPAN packaging specification.

## 11. REMARKS

- 11-1. Please refer to the "Handing procedures and remarks" before use.
- 11-2. Retention force for accommodated conductor specified in clause 9-4-3 differs due to different thickness, structure and surface treatment of conductor. Therefore, the value of retention force specified in the clause for performance is reference value.
- 11-3. Since this connector can not be used for CIC (Conductor such as silver paste, carbon etc.) as accommodated conductor, please consult us separately.

## 12. RECOMMENDED REFLOW PROFILE

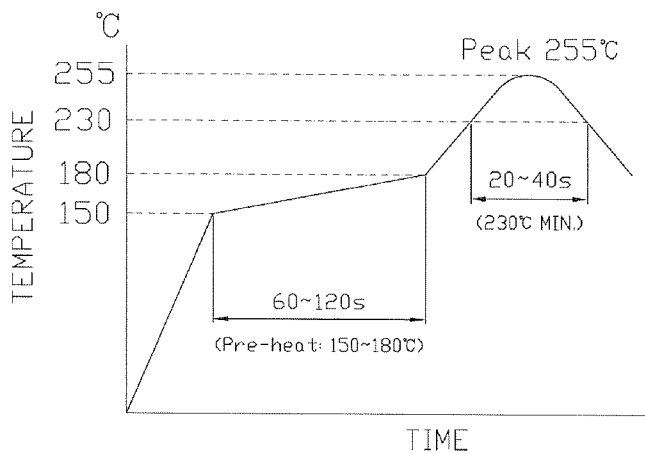



Diagram C. Recommended reflow temperature profile

Note: Please check the reflow soldering condition for your own application beforehand due to different conditions with soldering devices, P.C. Boards, etc.  
No moisture treatment before reflow process.

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13. REVISION RECORD

REV.	PAGE	DESCRIPTION	ECR#	DATE
A	ALL	RELEASE	J10-0028	2010-2-8
B	4	Operating temperature change from -55°C ~ +85°C to -55°C ~ +105°C	J10-0041	2010-2-19